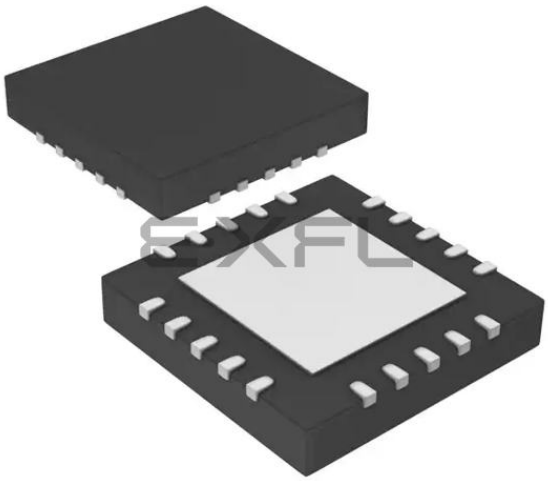


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	4KB (1.375K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-VQFN Exposed Pad
Supplier Device Package	20-VQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f04kl101-i-mq

SAMSUNG ELECTRO-MECHANICS

RoHS+Halogen Compliant ecoparts

SPECIFICATION (Reference sheet)

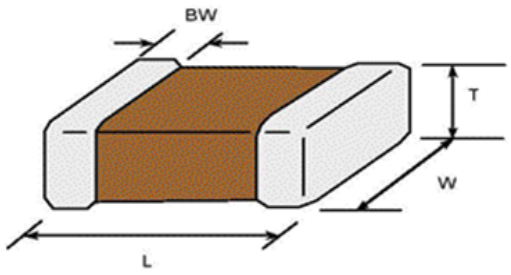
· **Supplier : Samsung electro-mechanics**
· **Product : Multi-layer Ceramic Capacitor**
· **Samsung P/N : CL21C102JCFNNNE**
· **Description : CAP, 1㎋, 100V, ± 5%, C0G, 0805**

A. Samsung Part Number

CL	21	C	102	J	C	F	N	N	N	E
①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩	⑪

①	**Series**	Samsung Multi-layer Ceramic Capacitor			
②	**Size**	0805 (inch code)	L: 2.00 ± 0.10 mm	W: 1.25 ± 0.10 mm	
③	**Dielectric**	C0G	⑧ **Inner electrode**	Ni	
④	**Capacitance**	1 ㎋	**Termination**	Cu	
⑤	**Capacitance tolerance**	± 5%	**Plating**	Sn 100%	(Pb Free)
			⑨ **Product**	Normal	
⑥	**Rated Voltage**	100 V	⑩ **Special**	Reserved for future use	
⑦	**Thickness**	1.25 ± 0.10 mm	⑪ **Packaging**	Embossed Type, 7" reel	

B. Structure and dimension



Samsung P/N (Lead Free)	Dimension(㎜)			
	L	W	T	BW
CL21C102JCFNNNE	2.00 ± 0.10	1.25 ± 0.10	1.25 ± 0.10	0.50+0.20/-0.30

C. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1㎒±10% / 0.5~5Vrms
Q	1,000 min	
Insulation Resistance	10,000Mohm or 500Mohm×㎌ Whichever is smaller	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Microscop (X10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	200% of the rated voltage
Temperature Characteristics	C0G (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g×F, for 10±1 sec.
Bending Strength	Capacitance change : within ±5% or ±0.5㎊ whichever is larger	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±2.5% or ±0.25㎊ whichever is larger Tan δ, IR : initial spec.	Solder pot : 270±5℃, 10±1sec.
Vibration Test	Capacitance change : within ±2.5% or ±0.25㎊ whichever is larger Tan δ, IR : initial spec.	Amplitude : 1.5mm From 10㎐ to 55㎐ (return : 1min.) 2hours ´ 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within ±7.5% or ±0.75㎊ whichever is larger Q : 200 min IR : 500Mohm or 25Mohm × ㎌ Whichever is smaller	With rated voltage 40±2℃, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within ±3% or ±0.3㎊ whichever is larger Q : 350 min IR : 1,000Mohm or 50Mohm × ㎌ Whichever is smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within ±2.5% or ±0.25㎊ whichever is larger Tan δ, IR : initial spec.	1 cycle condition Min. operating temperature → 25℃ → Max. operating temperature → 25℃ 5 cycle test

※ The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5℃, 10sec. Max)

⚠ Product specifications included in the specifications are effective as of March 1, 2013.
Please be advised that they are standard product specifications for reference only.
We may change, modify or discontinue the product specifications without notice at any time.
So, you need to approve the product specifications before placing an order.
Should you have any question regarding the product specifications,
please contact our sales personnel or application engineers.

- Disclaimer & Limitation of Use and Application -

*The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.*

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury.
*We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.*

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

① Aerospace/Aviation equipment
② Automotive or Transportation equipment (vehicles，trains，ships，etc)
③ Medical equipment
④ Military equipment
⑤ Disaster prevention/crime prevention equipment
⑥ Any other applications with the same as or similar complexity or reliability to the applications set forth above.